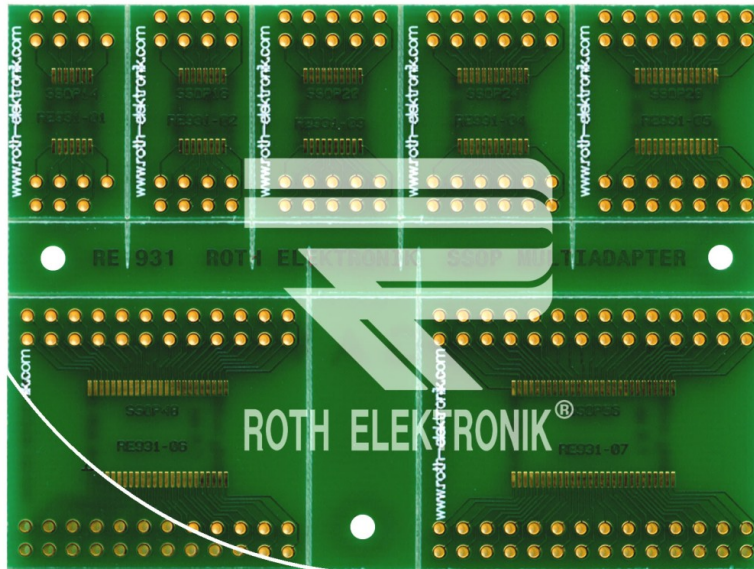


SSOP-SMD Multiadapter (shrink small outline package)



RE931



- EPOXY fibre glass FR4 1.5 mm double-sided 35 µm CU (pth)
- solder and component side with chem. NI/AU surface and solder stop mask
- hole dia 1.00 mm
- adapter for 7 different SSOP
- pitch 0.65 mm / 0.635 mm
- pre-scratched rated break points for the separation of individual modules from the board
- size 61.40 x 81.70 mm

| Modul-No | Pitch | mil | Pin/Quantity | Size (mm) |
|----------|-------|------|--------------|---------------|
| RE931-01 | 0.65 | 22.5 | 14 | 5.3 (208 mil) |
| RE931-02 | 0.65 | 22.5 | 16 | 5.3 (208 mil) |
| RE931-03 | 0.65 | 22.5 | 20 | 5.3 (208 mil) |
| RE931-04 | 0.65 | 22.5 | 24 | 5.3 (208 mil) |
| RE931-05 | 0.65 | 22.5 | 28 | 5.3 (208 mil) |
| RE931-06 | 0.635 | 25.7 | 48 | 7.5 (300 mil) |
| RE931-07 | 0.635 | 25.7 | 56 | 7.5 (300 mil) |